

## Charge collection in proton irradiated HV-CMOS sensors

31st RD50 Workshop (CERN), 22.11.2017

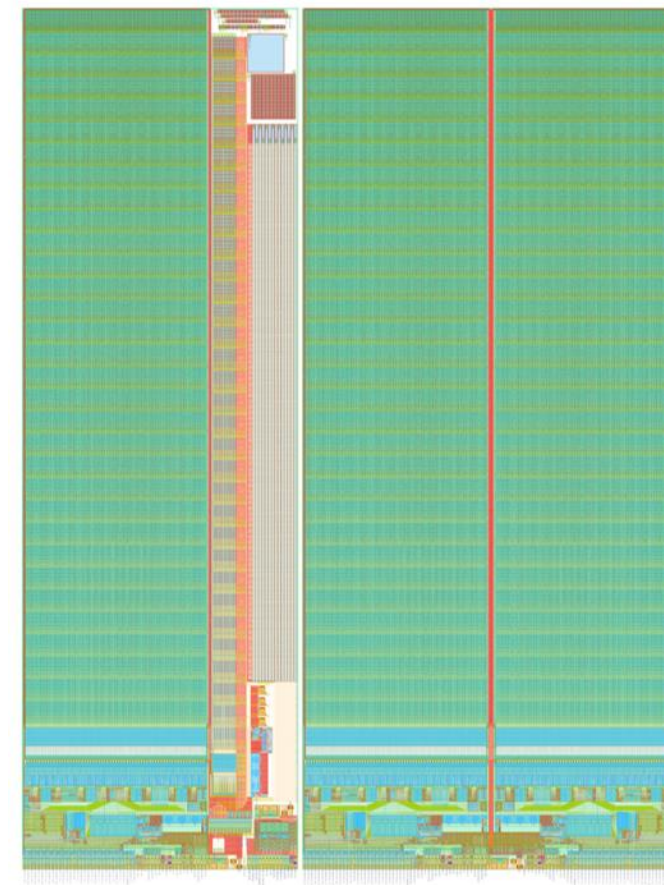
Bojan Hiti,

Jožef Stefan Institute, Experimental Particle Physics Department (F9), Ljubljana, Slovenia



- CHESS 2 chip (designed at UCSC and SLAC, manufactured in the AMS-H35 technology by AMS)
- Full reticle monolithic demonstrator chip of the ATLAS Strip CMOS project
- 3 fully digital triplet arrays, 1 test field with analog test structures
- $n$  in  $p$
- 4 substrate resistivities (20 – 1000  $\Omega\cdot\text{cm}$ )
- Same wafer material also used in production of the AtlasPix chip (monolithic pixel CMOS chip)

	Size
<b>Height</b>	18.6 mm
<b>Width</b>	24.3 mm
<b>Thickness</b>	250 $\mu\text{m}$
<b>Standard resistivity</b>	20 $\Omega\cdot\text{cm}$
<b>Resistivity 2</b>	50-100 $\Omega\cdot\text{cm}$
<b>Resistivity 3</b>	200-300 $\Omega\cdot\text{cm}$
<b>Resistivity 4</b>	600-2000 $\Omega\cdot\text{cm}$



H. Grabas, FEE 2016:  
<https://indico.cern.ch/event/522485/>



# Irradiation campaigns

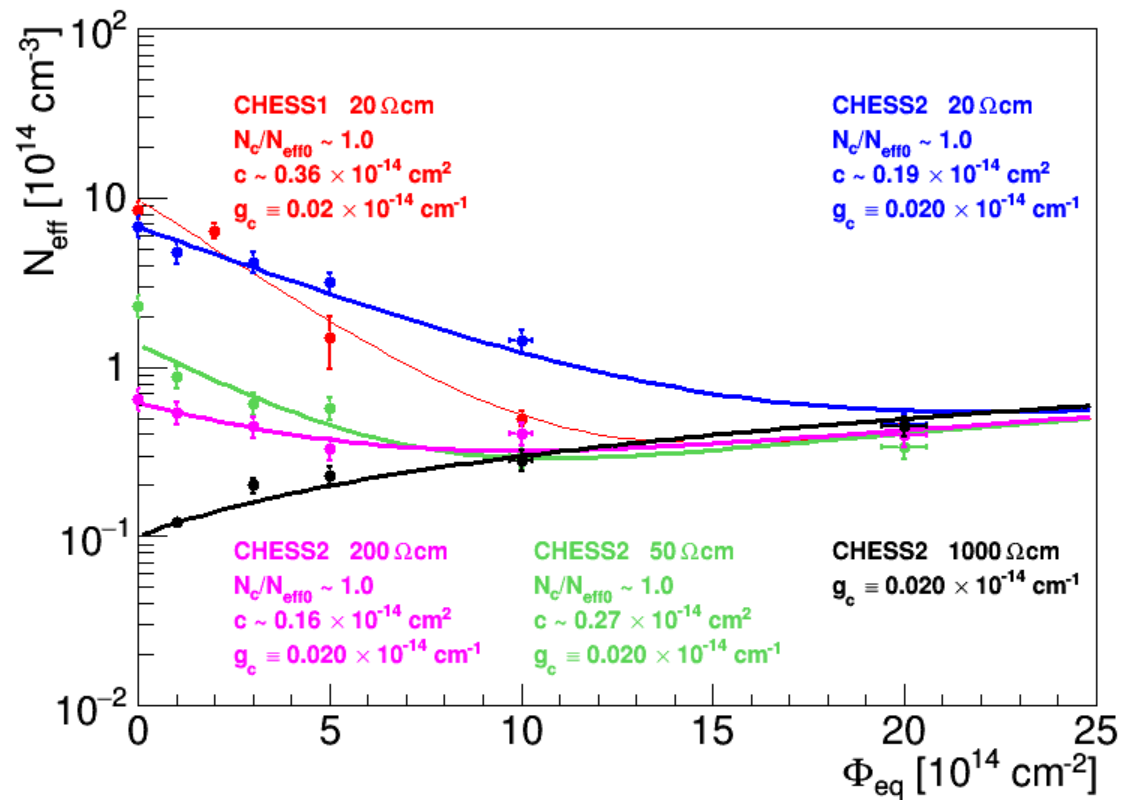
- Irradiation hardness studies with CHES 2 carried out in Ljubljana:
    - reactor neutrons (Ljubljana) – 4 resistivities, 5 fluences ( $1e14 - 2e15 n_{eq}/cm^2$ )
    - 24 GeV protons (CERN PS) – 3 resistivities, 2 fluences
    - 800 MeV protons (Los Alamos LANSCE) – 4 resistivities, 3 fluences
- } focus of this talk
- Characterization of passive structures using Edge-TCT and  $Sr^{90}$
  - Measurements before and after annealing (80 min at 60 °C)

Table of proton irradiated samples/fluences

$\phi$ ( $10^{14} n_{eq} cm^{-2}$ )	20 $\Omega \cdot cm$	50 $\Omega \cdot cm$	200 $\Omega \cdot cm$	1000 $\Omega \cdot cm$
0				breakdown
4.2	CERN PS	n.a.	CERN PS	CERN PS
7.7	Los Alamos	Los Alamos	Los Alamos	Los Alamos
8.7	CERN PS	n.a.	CERN PS	CERN PS
14	n.a.	Los Alamos	Los Alamos	n.a.
36	n.a.	Los Alamos	Los Alamos	n.a.

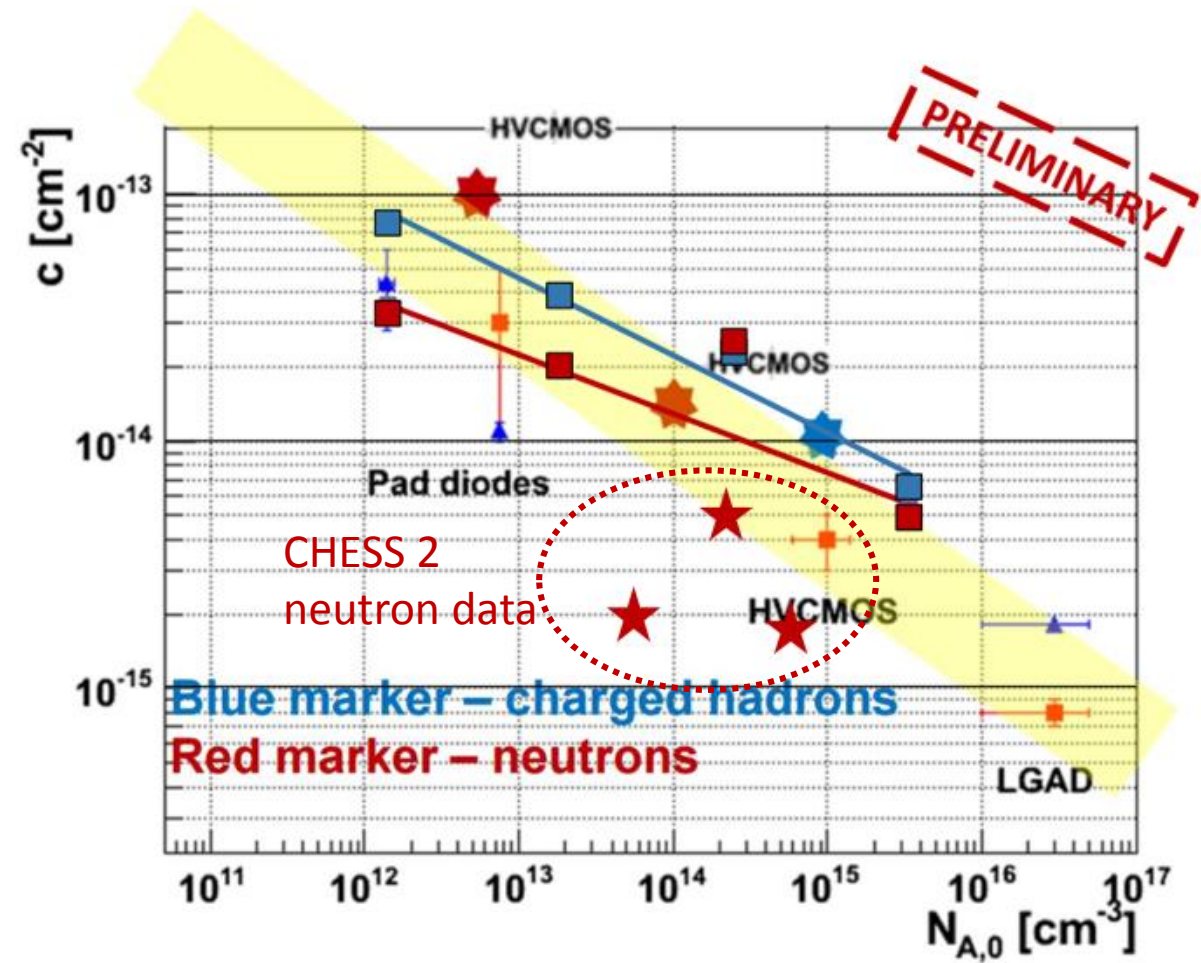


# Reminder: neutron irradiation



Neutron irradiation results presented in Trento 2017

[Link](#)

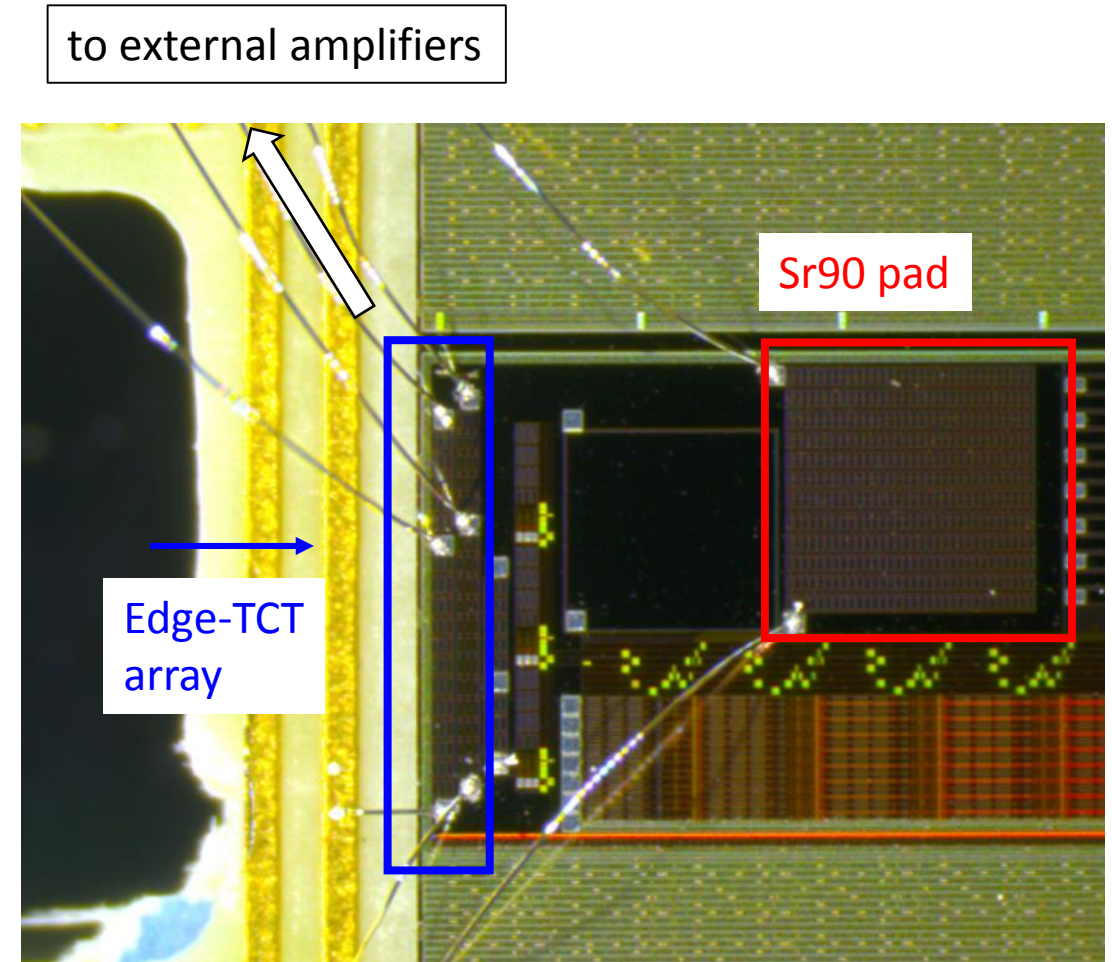


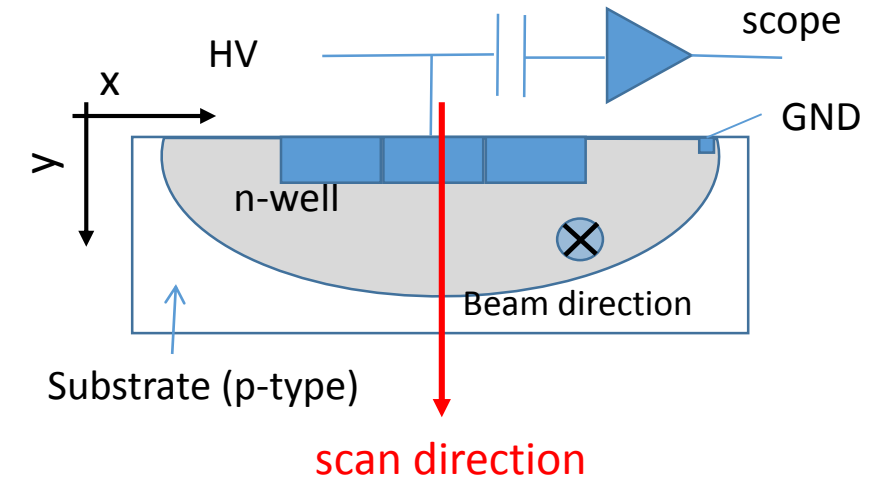
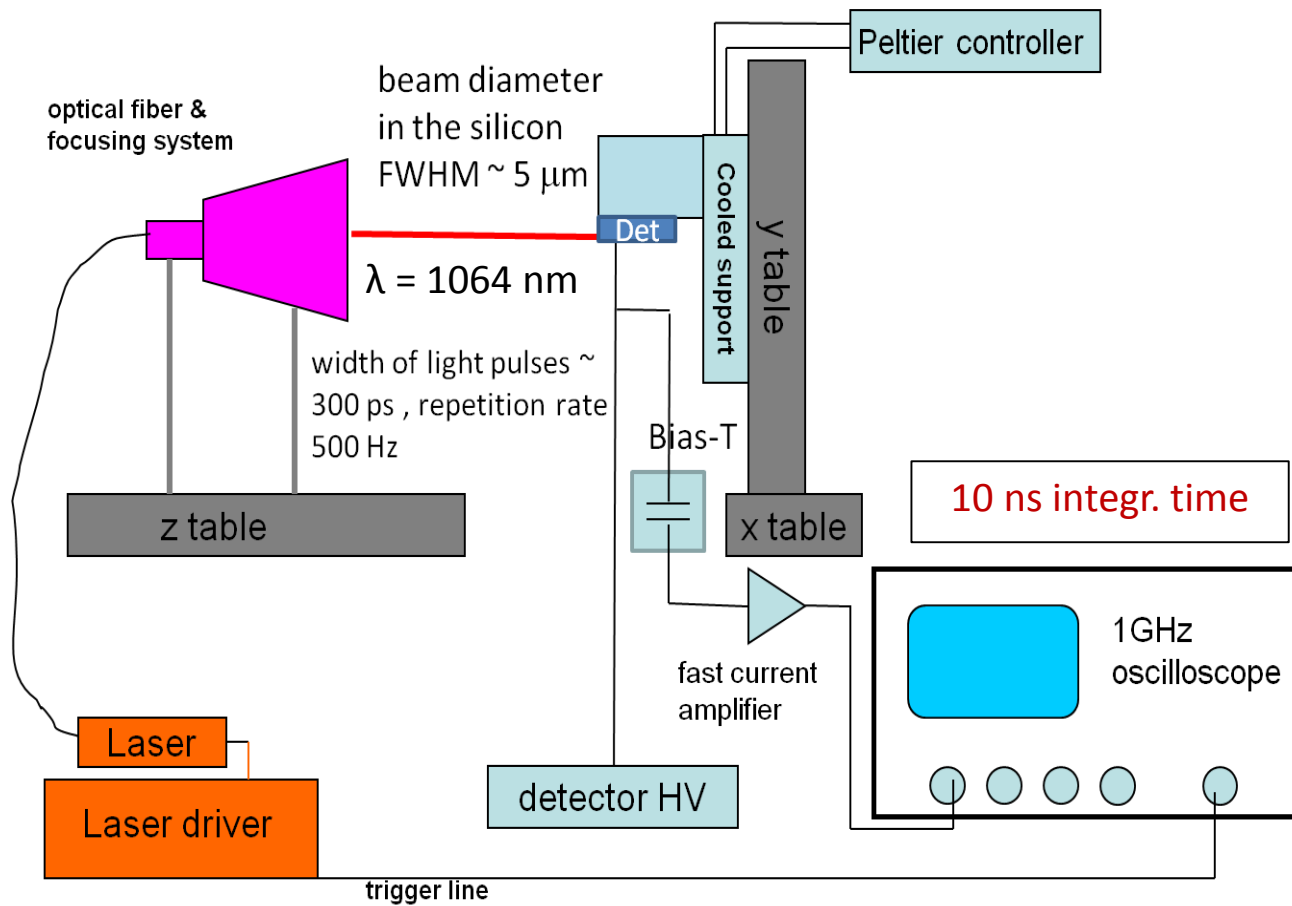
P. Dias de Almeida, 30th RD50 Workshop 2017

Passive test structures:

- 3 x 3 pixel array for Edge-TCT (pixel size  $630 \times 40 \mu\text{m}^2$ )
- Large pad for Sr90 measurements ( $1.2 \times 1.2 \text{ mm}^2$ )

Bias voltage up to 120 V can be applied

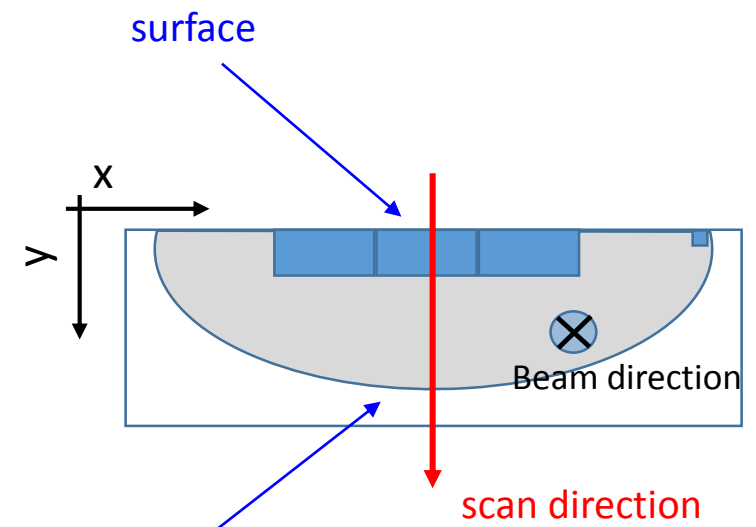
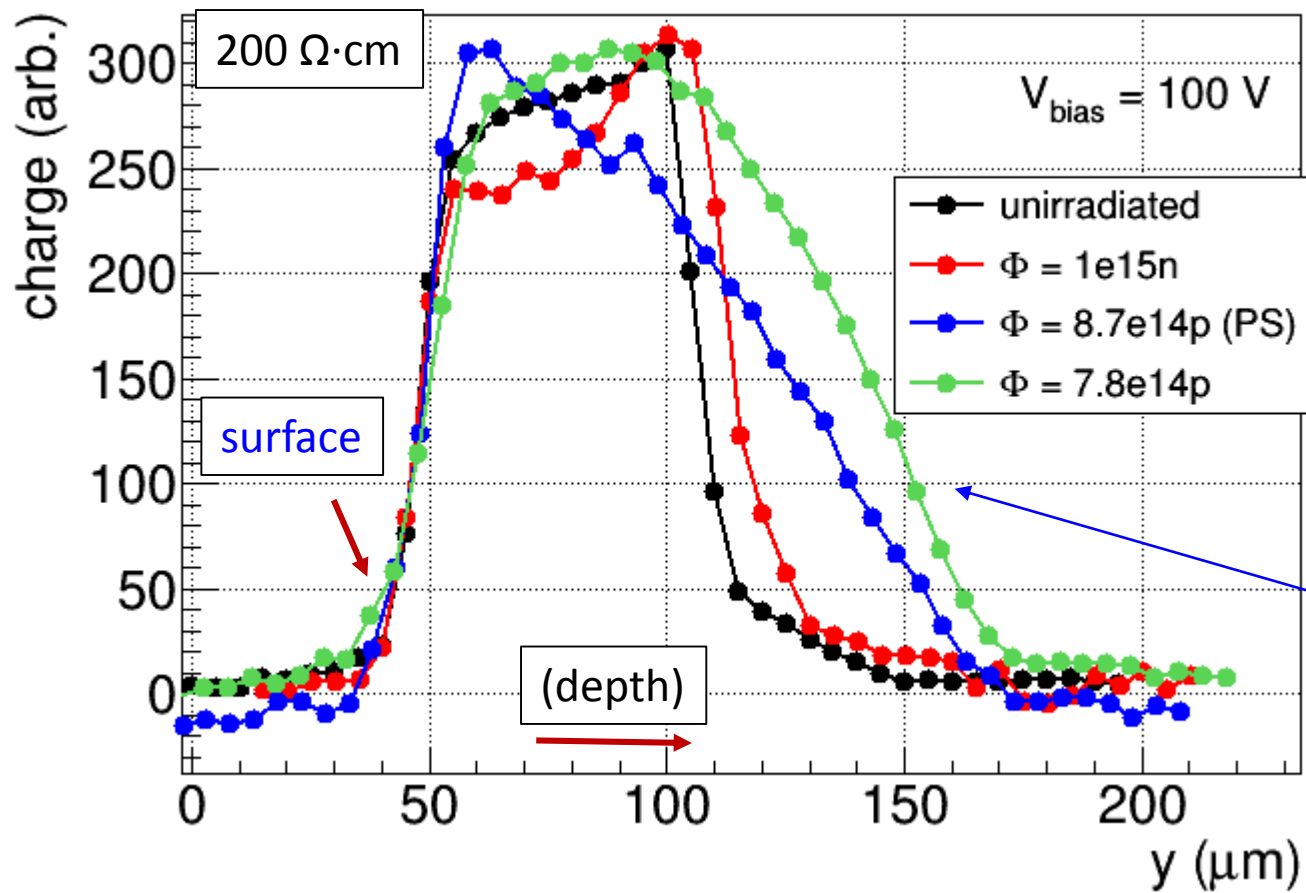




- Standard Edge-TCT measurements (Particulars setup)
- Scan along the middle of the central pixel

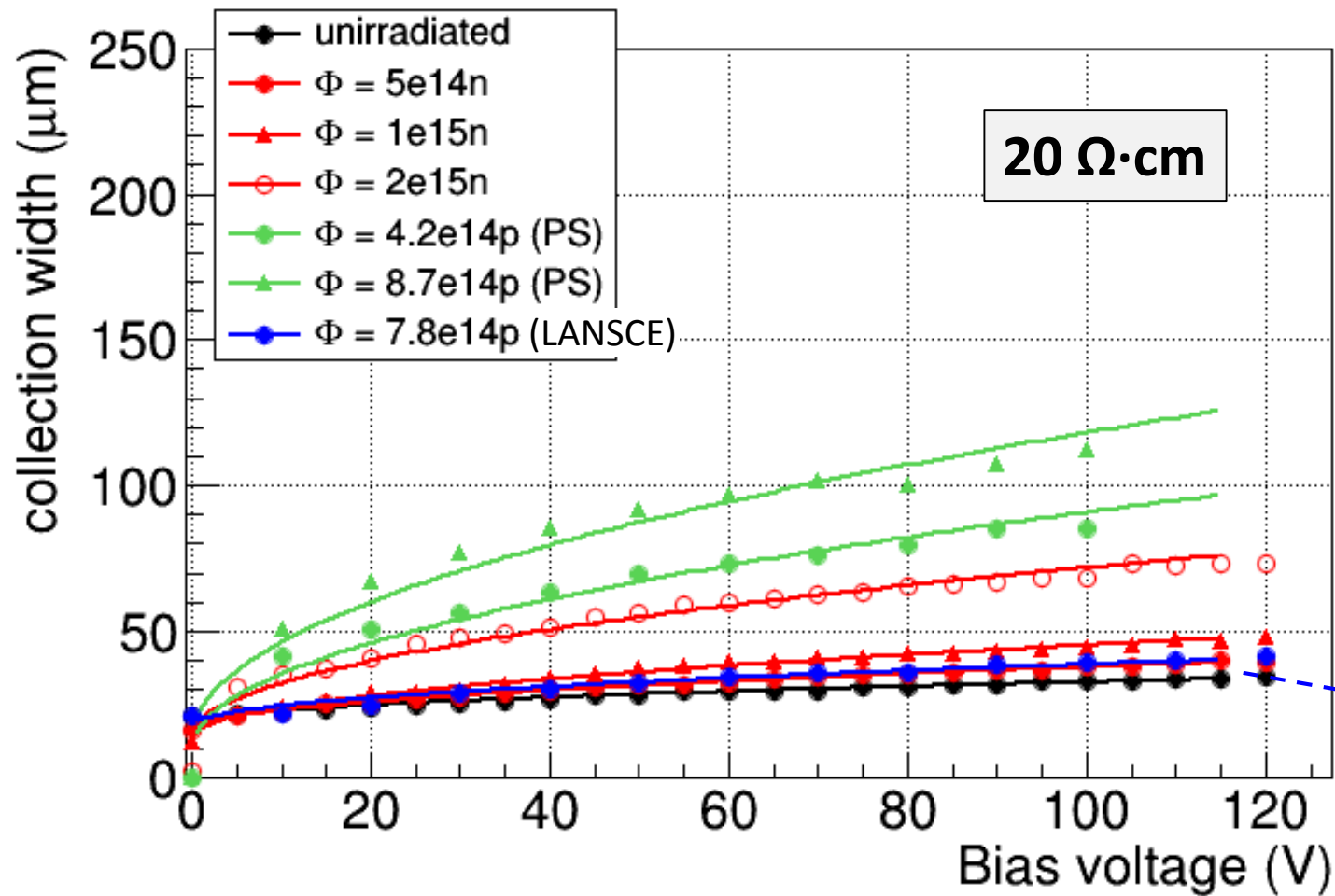
( more details: [www.particulars.si](http://www.particulars.si) )





- After proton irradiation significant increase in charge collection width is observed (even compared to neutrons)
- Depleted depth is evaluated as width of the charge collection profile

# Depletion vs. bias voltage (20 Ω·cm)

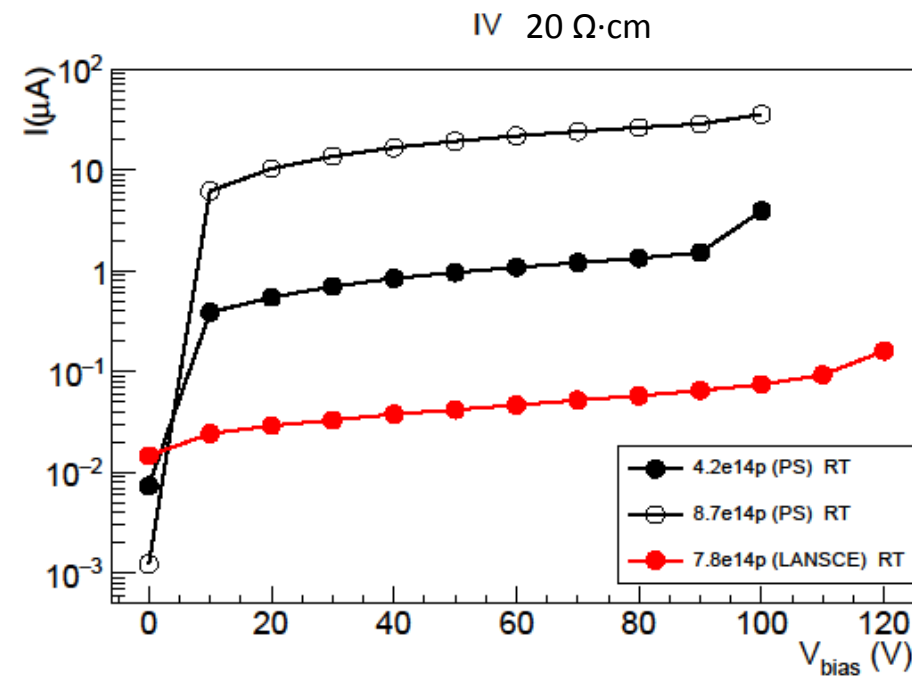
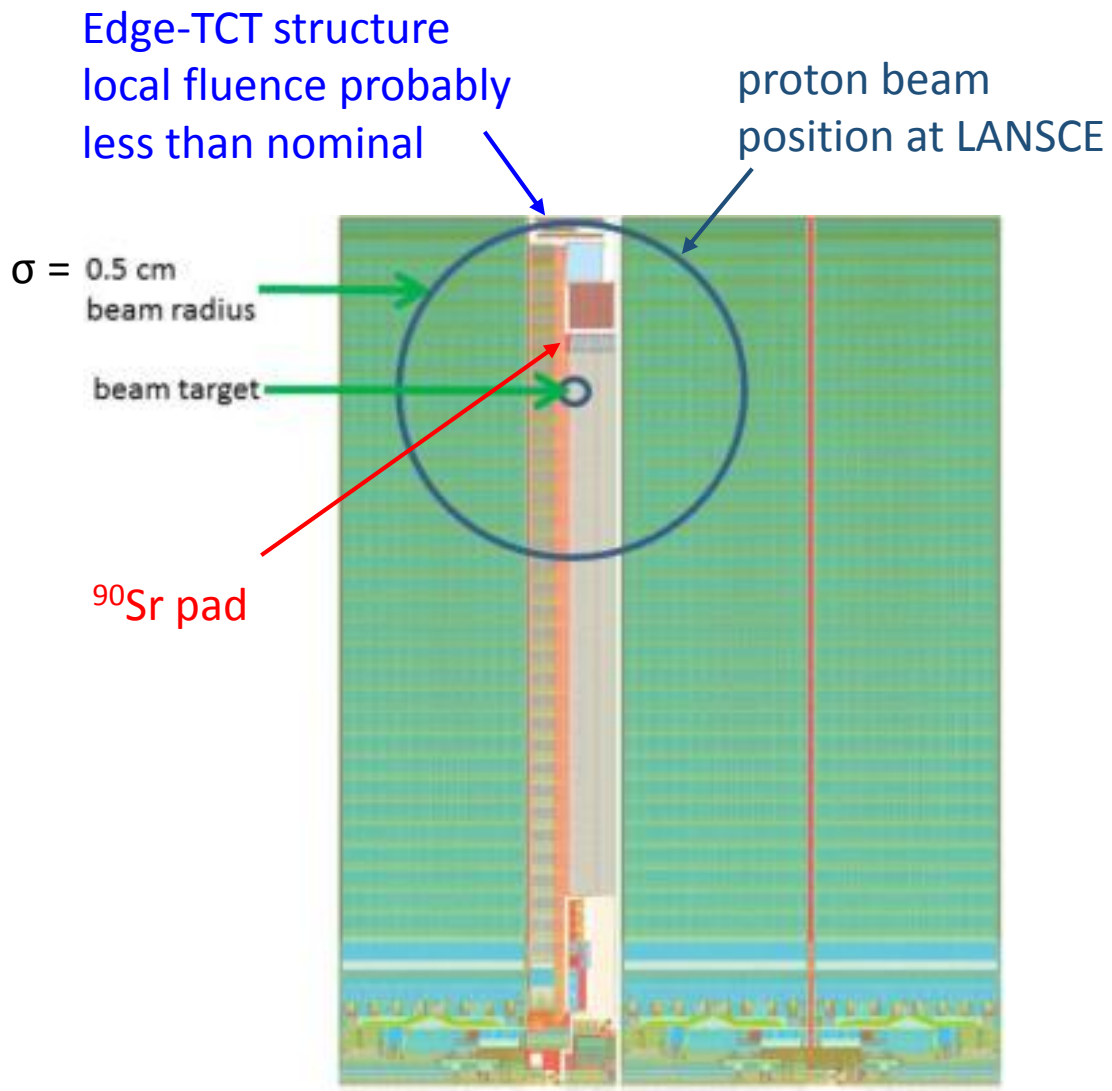


$N_{\text{eff}}$  is extracted from voltage dependence by fitting:

$$\text{Width}(V_{\text{bias}}) = w_0 + \sqrt{\frac{2\epsilon\epsilon_0}{e_0 N_{\text{eff}}}} V_{\text{bias}}$$

LANSCÉ sample different from PS samples



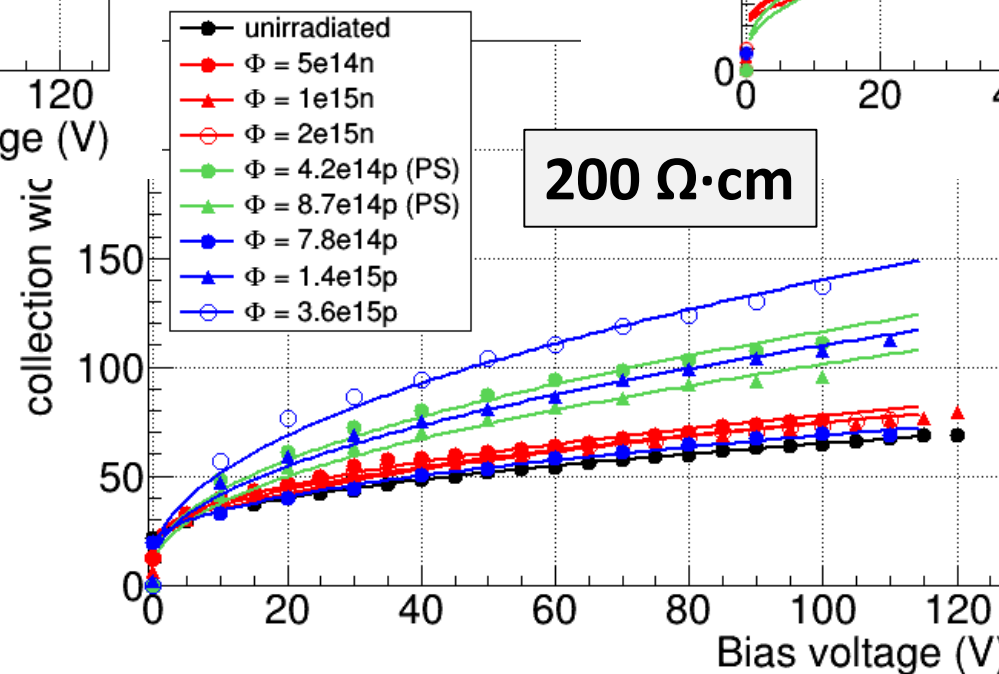
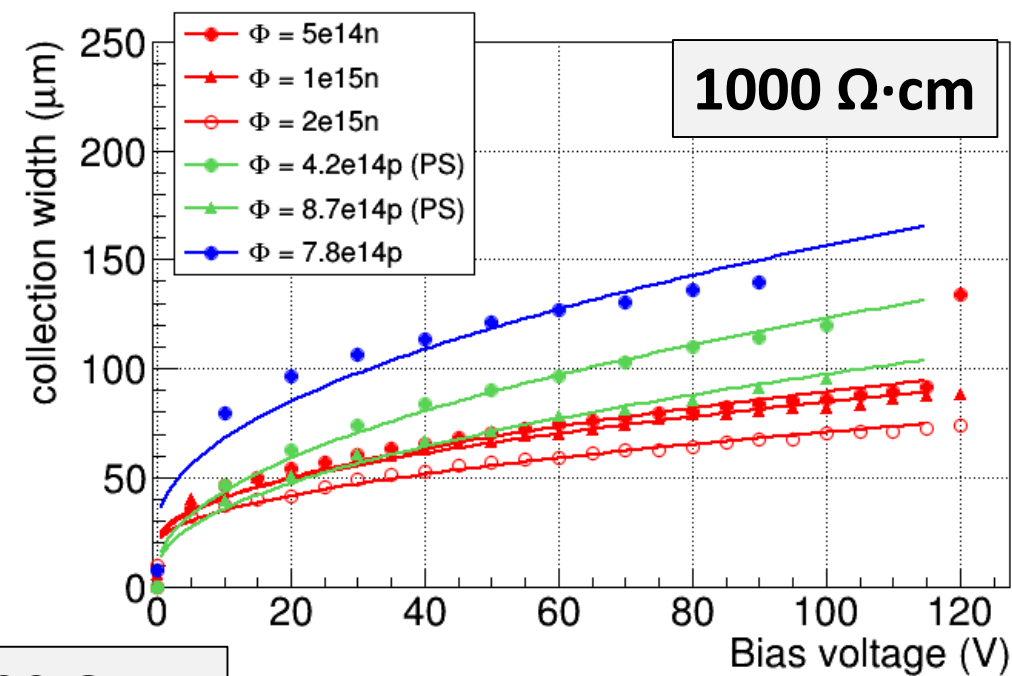
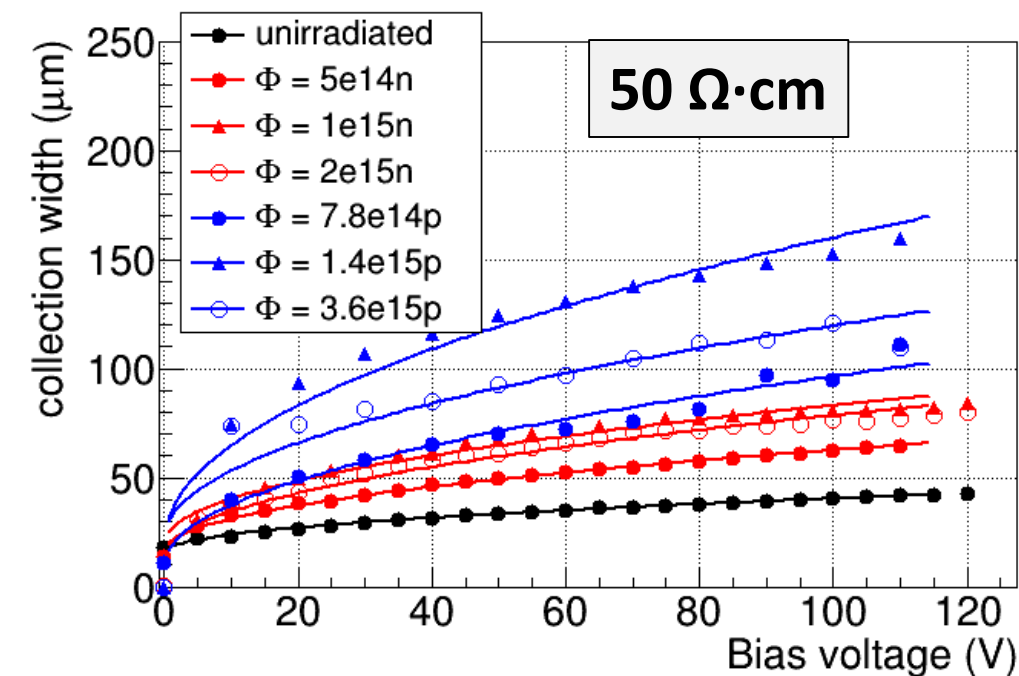


Due to the beam position at LANSCE the received fluence in the Edge-TCT structure is relatively sensitive to placement precision.

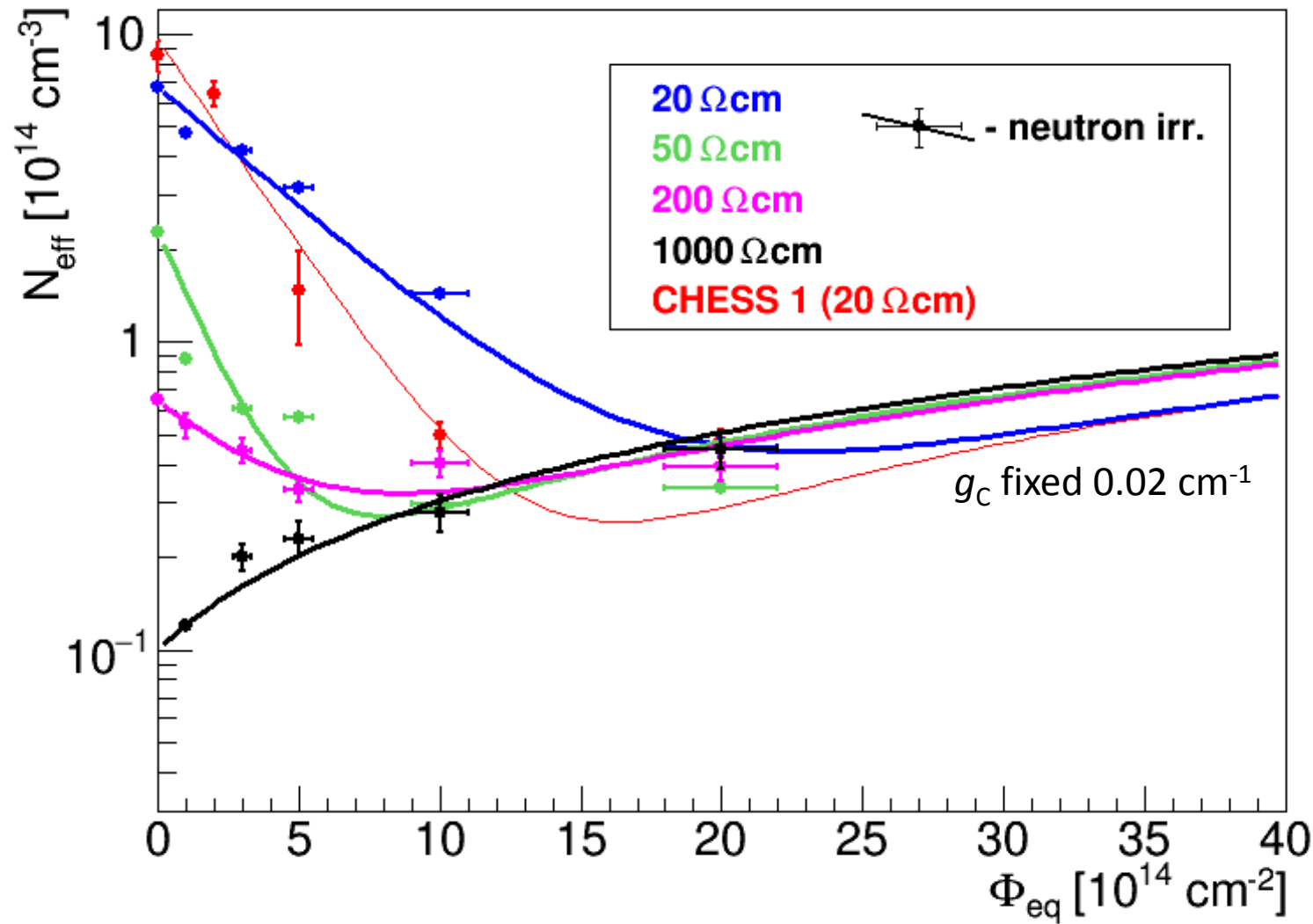
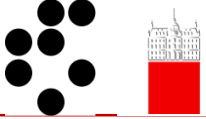
Large error margins on fluence have to be assumed.



# Depletion depth at remaining resistivities



Proton irradiated samples have in general a larger depletion depth than neutron irradiated ones



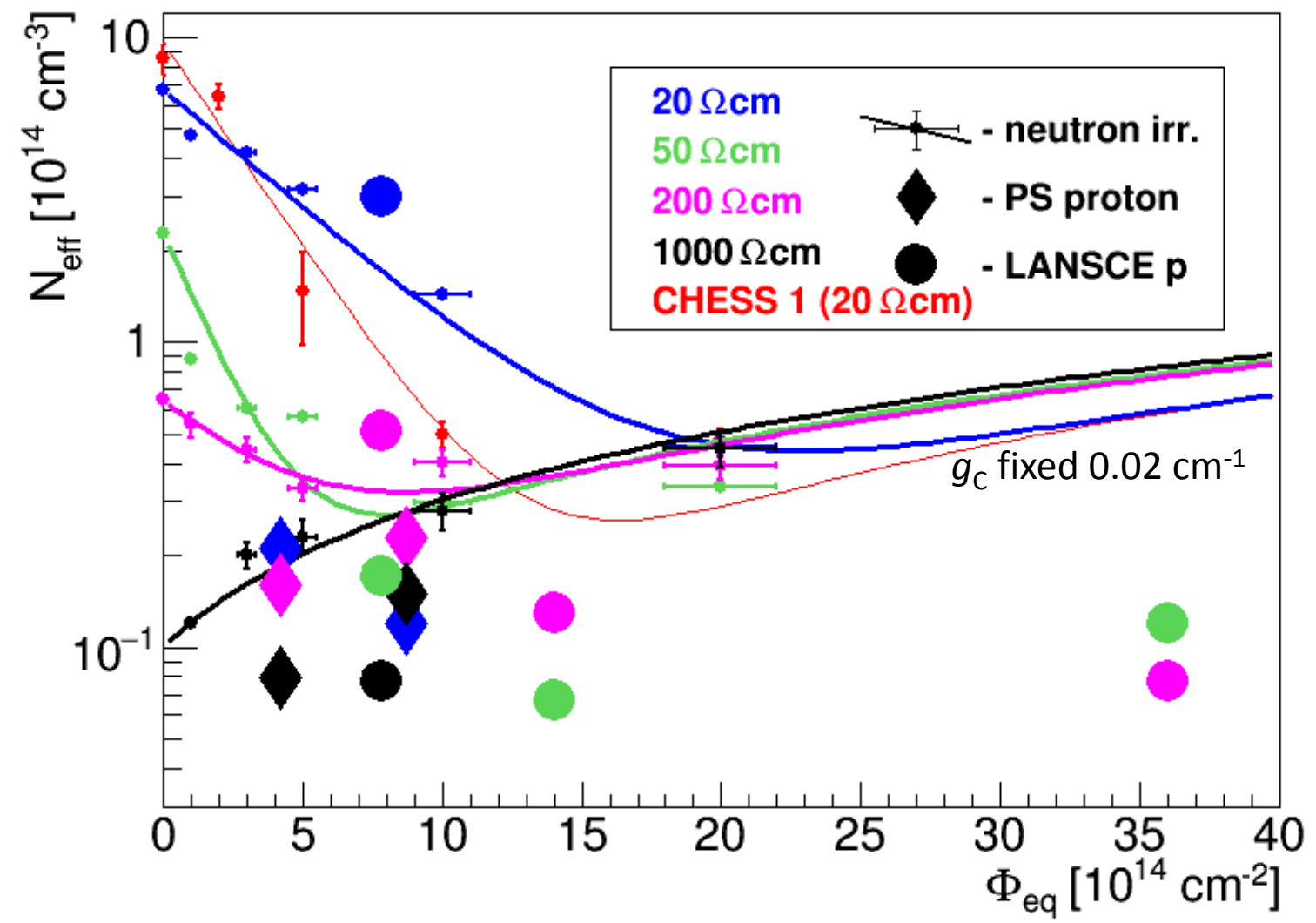
$$N_{\text{eff}} = N_{\text{eff0}} - \underbrace{N_c \cdot (1 - \exp(-c \cdot \Phi_{\text{eq}}))}_{\text{acceptor removal}} + \underbrace{g_c \cdot \Phi_{\text{eq}}}_{\text{acceptor introduction}}$$

acceptor removal acceptor introduction

**Neutrons only**

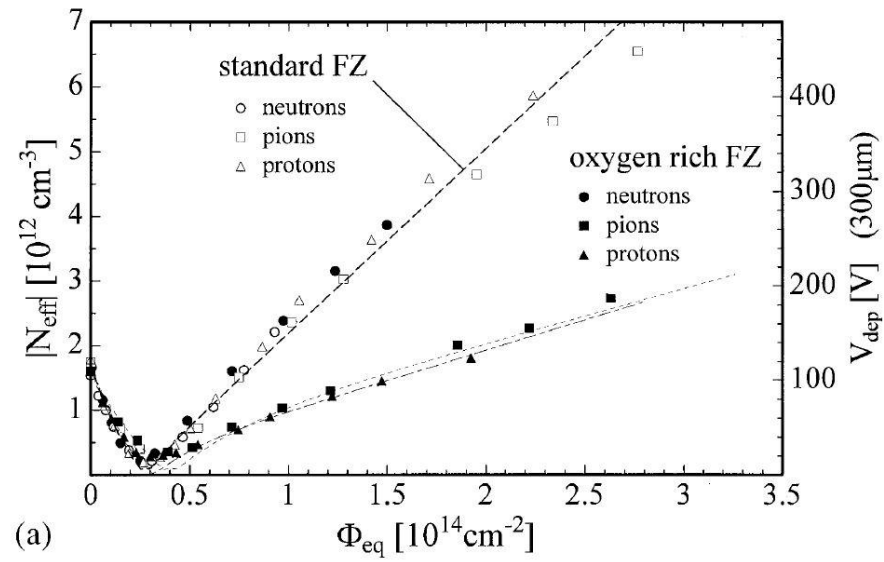


# Effective space charge concentration



$$N_{\text{eff}} = N_{\text{eff}0} - N_c \cdot (1 - \exp(-c \cdot \Phi_{\text{eq}})) + g_C \cdot \Phi_{\text{eq}}$$

- Acceptor introduction rate lower with protons than with neutrons
- Common in oxygenated silicon



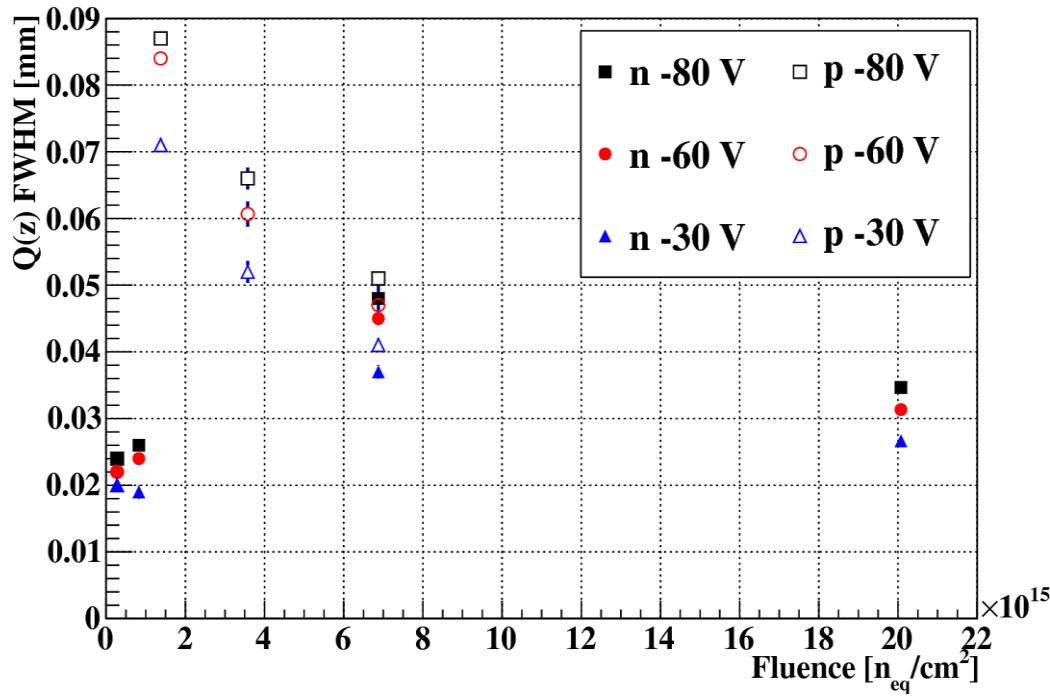
(a)

- Possibly large errors on received proton fluence
- Acceptor removal parameters for protons cannot be determined due to a small number of measurement points



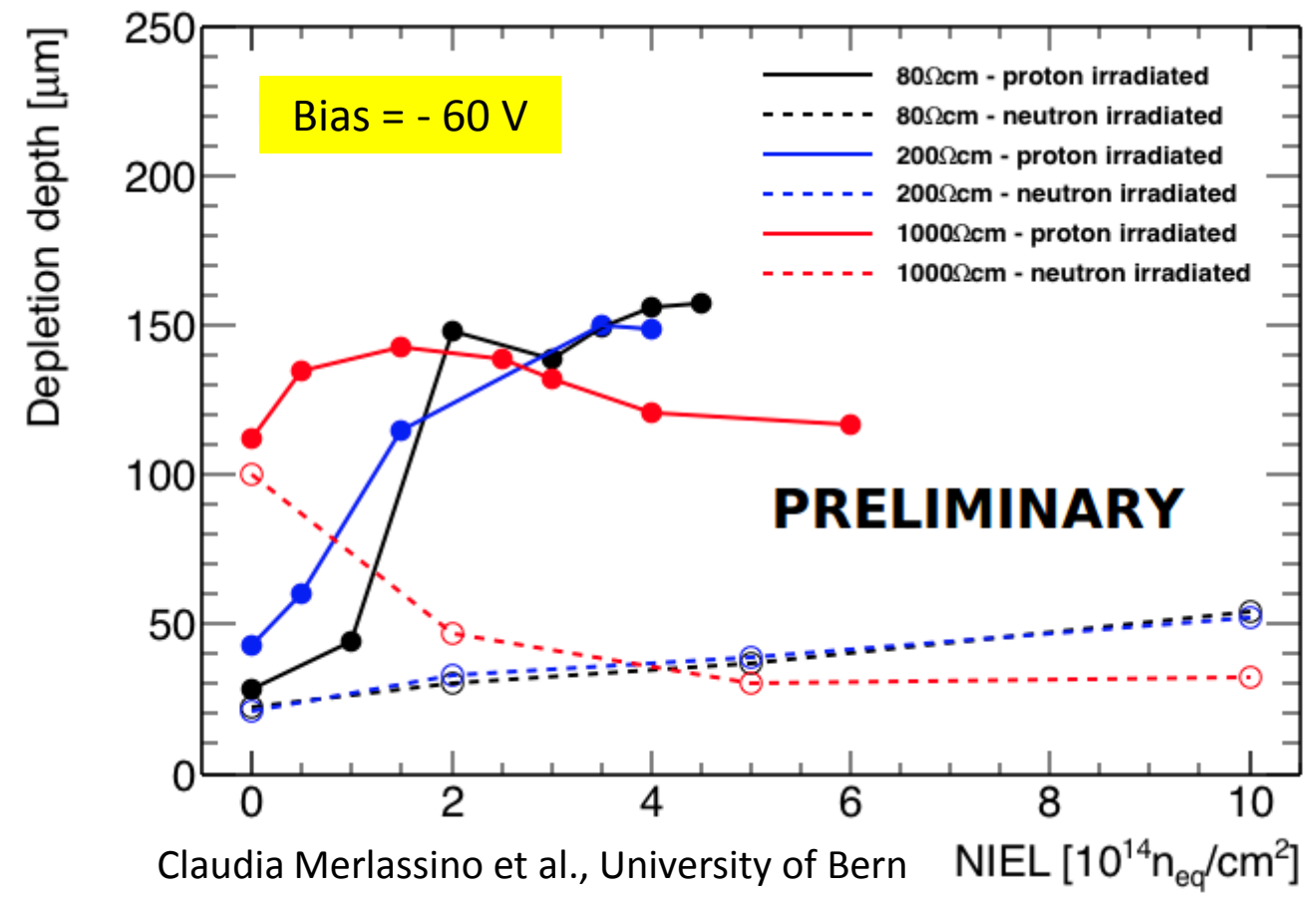
# Other measurements with proton irradiated samples

AMS H18 10 Ωcm (CCPDv3)  
Depleted depth vs fluence:



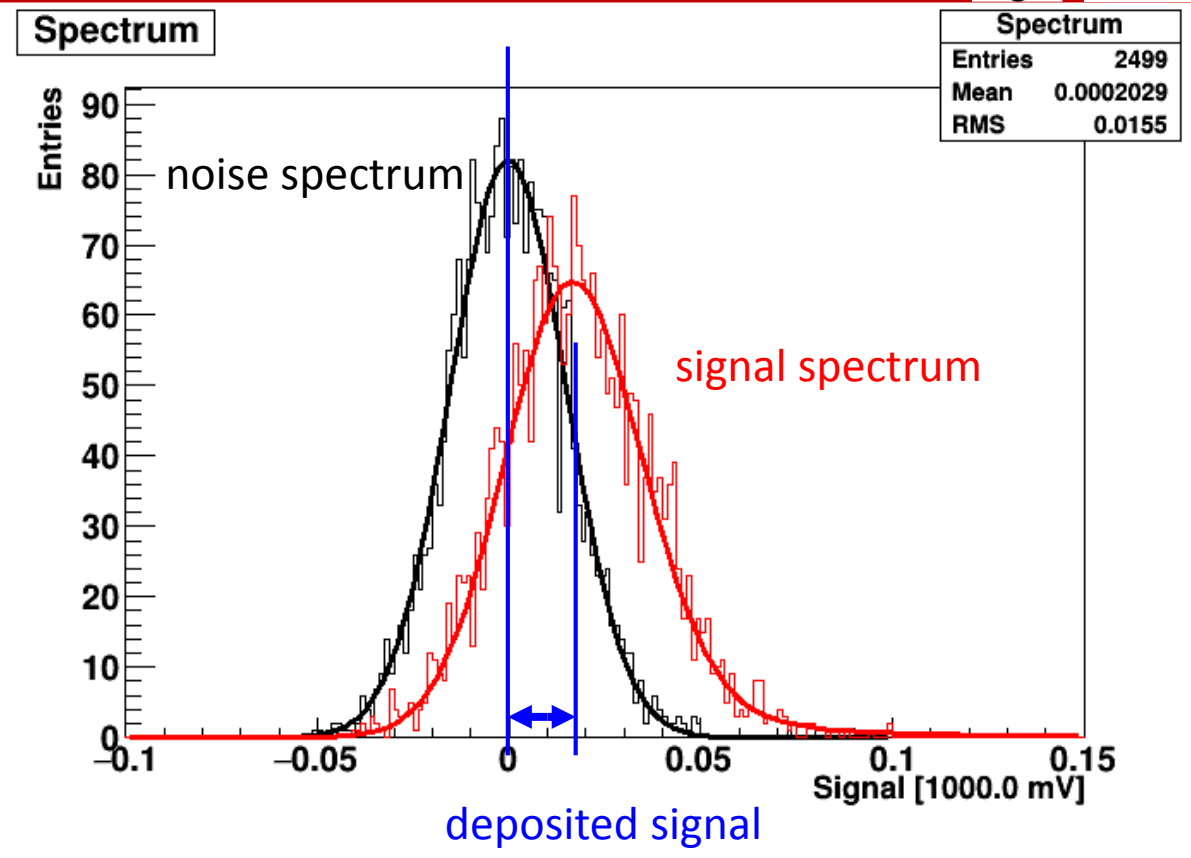
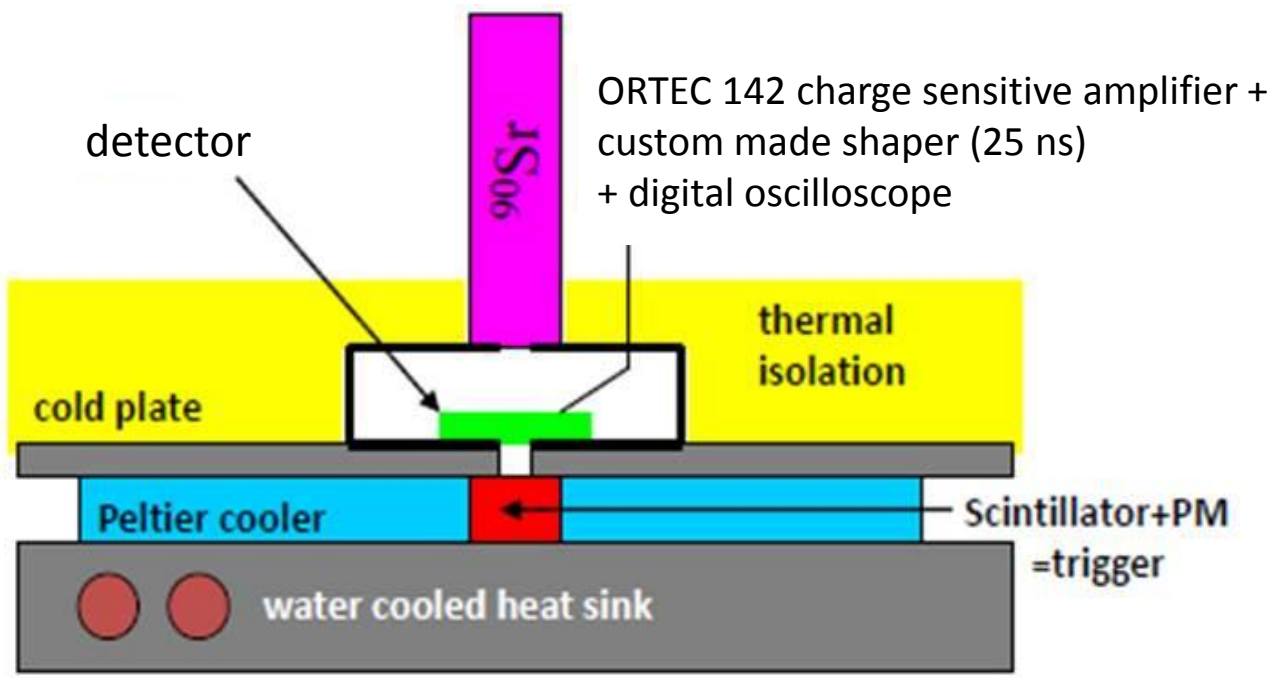
M. Fernández, 27th RD50 workshop, December 2015

AMS H35 DEMO  
Proton irradiation at Bern (18 MeV p)



Claudia Merlassino et al., University of Bern NIEL [ $10^{14} n_{eq}/cm^2$ ]

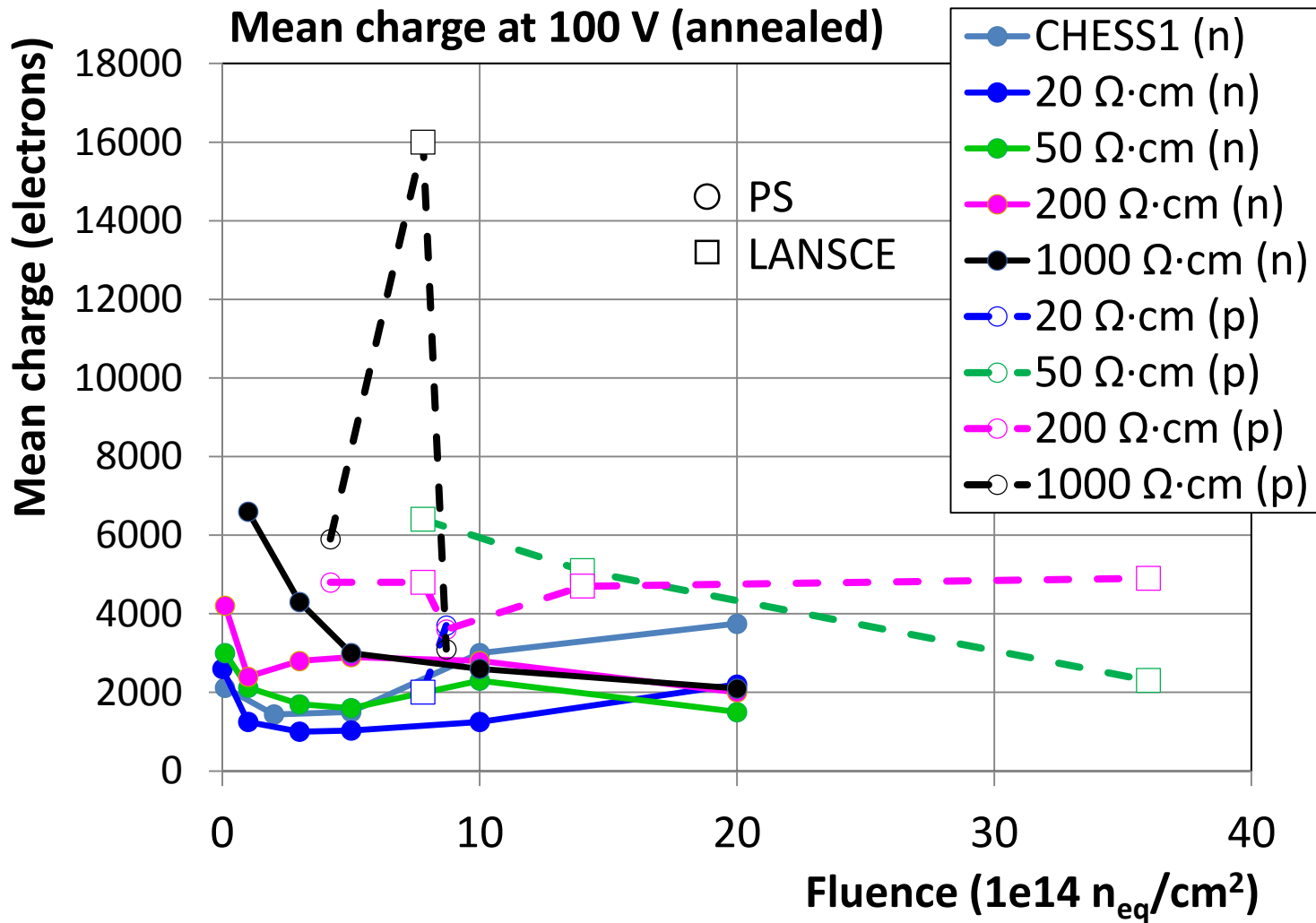
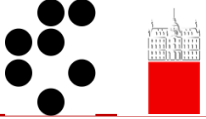
All measurements show very large depletion depth compared to neutron irradiated samples



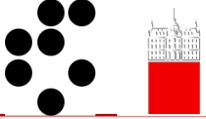
## • Measurement:

- 1) Record  $N$  ( $= 2500$ ) waveforms
  - 2) Determine peaking time from the average waveform
  - 3) Sample waveforms at the peak and fill the spectrum
  - 4) Fit the spectrum with a convoluted landau + gauss function
- HV-CMOS: small signals, large noise  $\rightarrow$  S/N low
  - Signal strength determined from the shift between triggered and noise spectrum
  - System calibrated with epi-diodes of known size

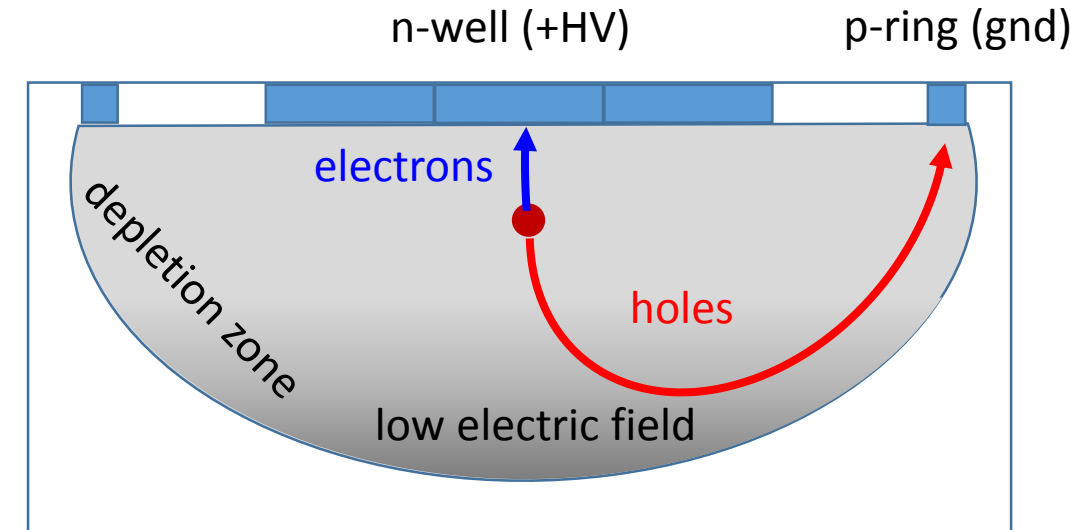


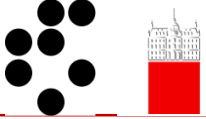


- More charge collected in proton irradiated than in neutron irradiated sample at any fluence/resistivity
- Acceptor removal:  
at certain fluences collected charge is more than before irradiation
- Annealing (not shown)  
10 % more charge after 80 min at 60 °C
- Very constant response of 200  $\Omega\cdot\text{cm}$  sample with respect to fluence (both n and p)
- In 50  $\Omega\cdot\text{cm}$  and 200  $\Omega\cdot\text{cm}$  depletion depth of  $> 100 \mu\text{m}$  measured with Edge-TCT
  - Expected mean charge  $> 10000 e^-$
  - Observed charge  $< 5000 e^-$



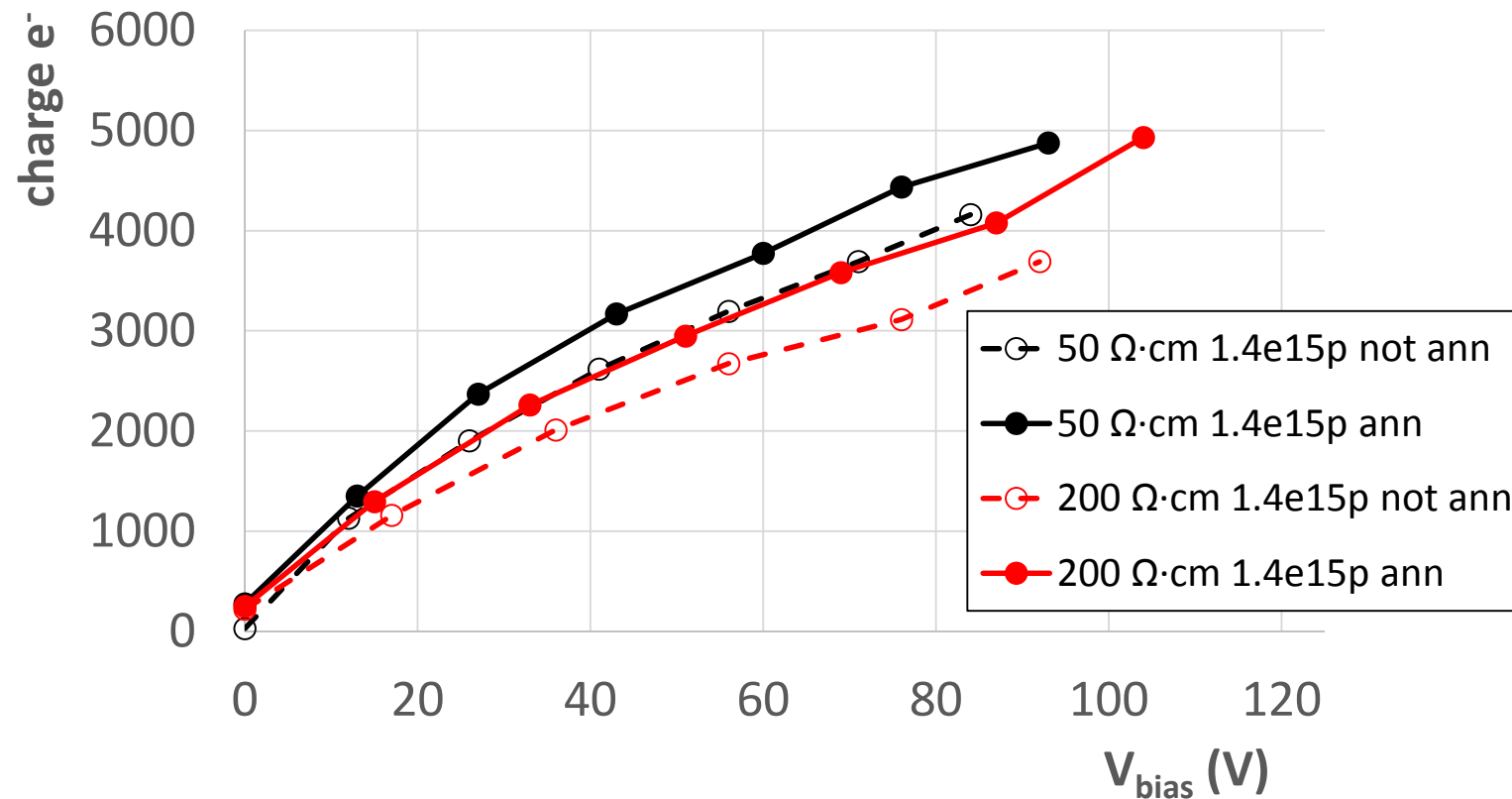
- In irradiated samples  $\approx 50\%$  less charge collected ( $^{90}\text{Sr}$ ) than expected from Edge-TCT
- The reason for low CCE is due to sensor biasing from the top
  - Drift of both types of charge carriers ends on the chip surface
  - Holes have to drift through a low  $E$  region, where trapping is high
  - Trapped charge carriers only pass a part of the weighting field
  - The effect is **strongly mitigated** by **thinning** and **back plane metalization**
  - Observed in LFoundry CMOS chips with and without processed back plane





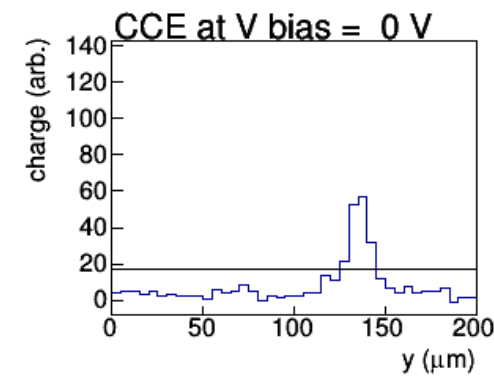
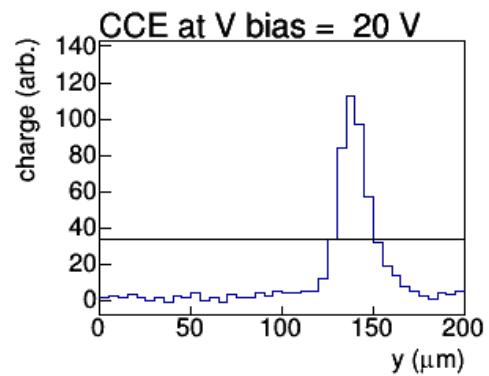
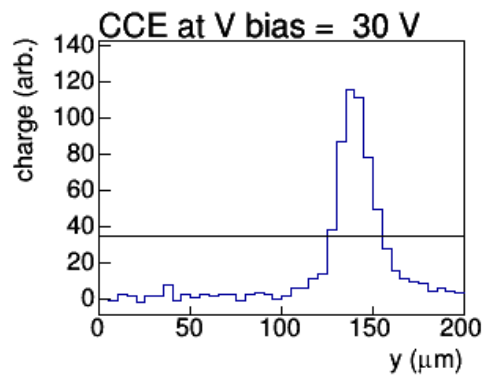
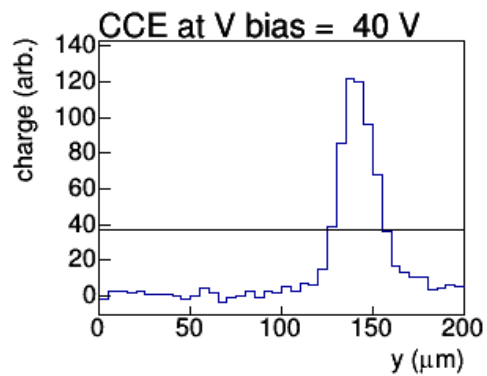
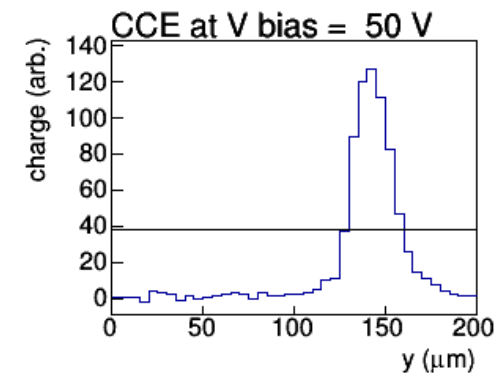
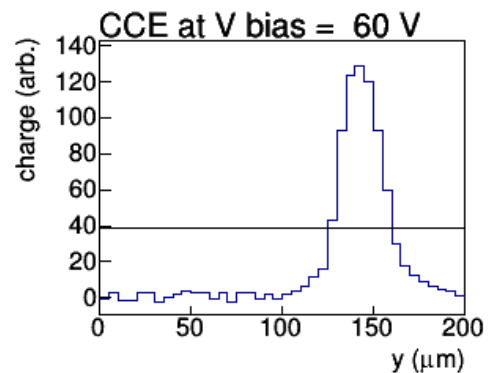
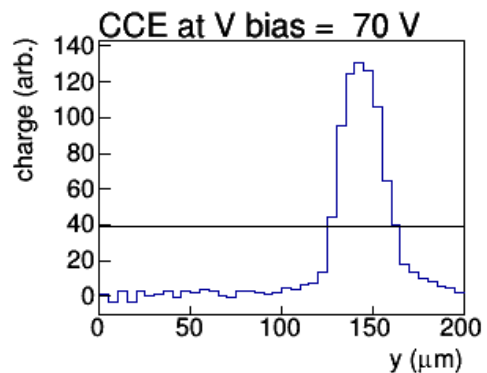
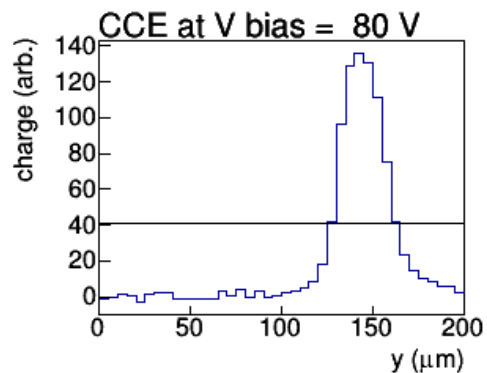
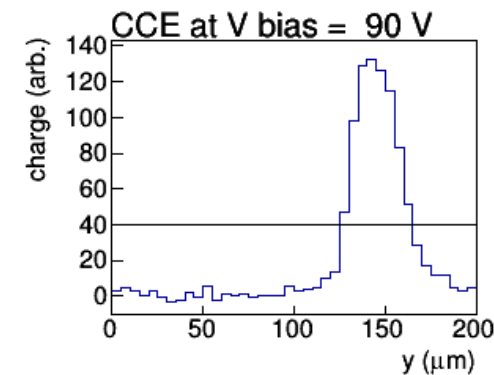
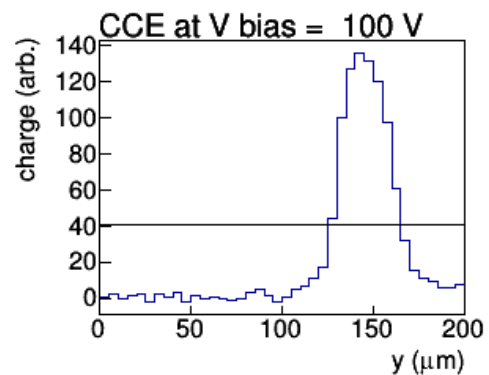
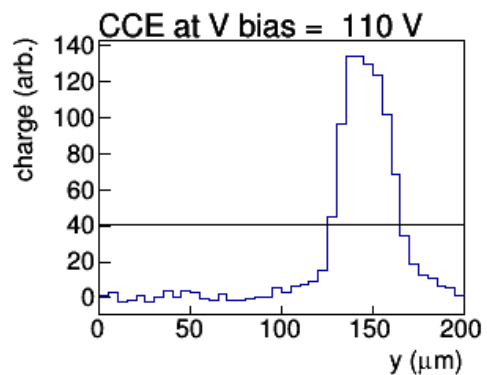
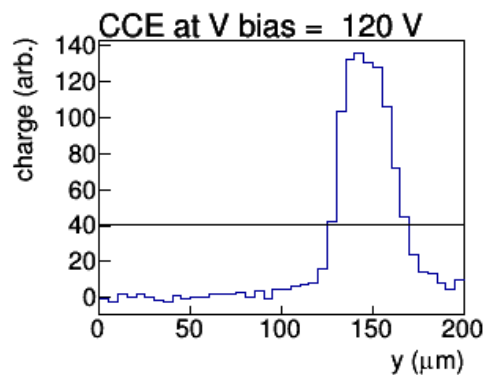
- Extensive sensor radiation hardness study conducted with AMS CHES 2 samples of different resistivities
  - Proton irradiated, compared to an earlier neutron irradiation
  - Edge-TCT,  $^{90}\text{Sr}$  measurements
- Acceptor removal observed in proton irradiated samples
  - **Larger depletion depth** and **greater charge** collected than with neutron irradiated samples **at all fluences and resistivities**
  - Lower acceptor introduction rate than with neutrons
  - Insufficient number of measurement points to determine acceptor removal parameters
- Less charge collected than expected for a measured depletion depth
  - Metalized backplane and back biasing is required
- Large uncertainty on received proton fluence
  - Small dedicated detectors or scanning beam better suited to achieve uniform irradiation level

BACKUP



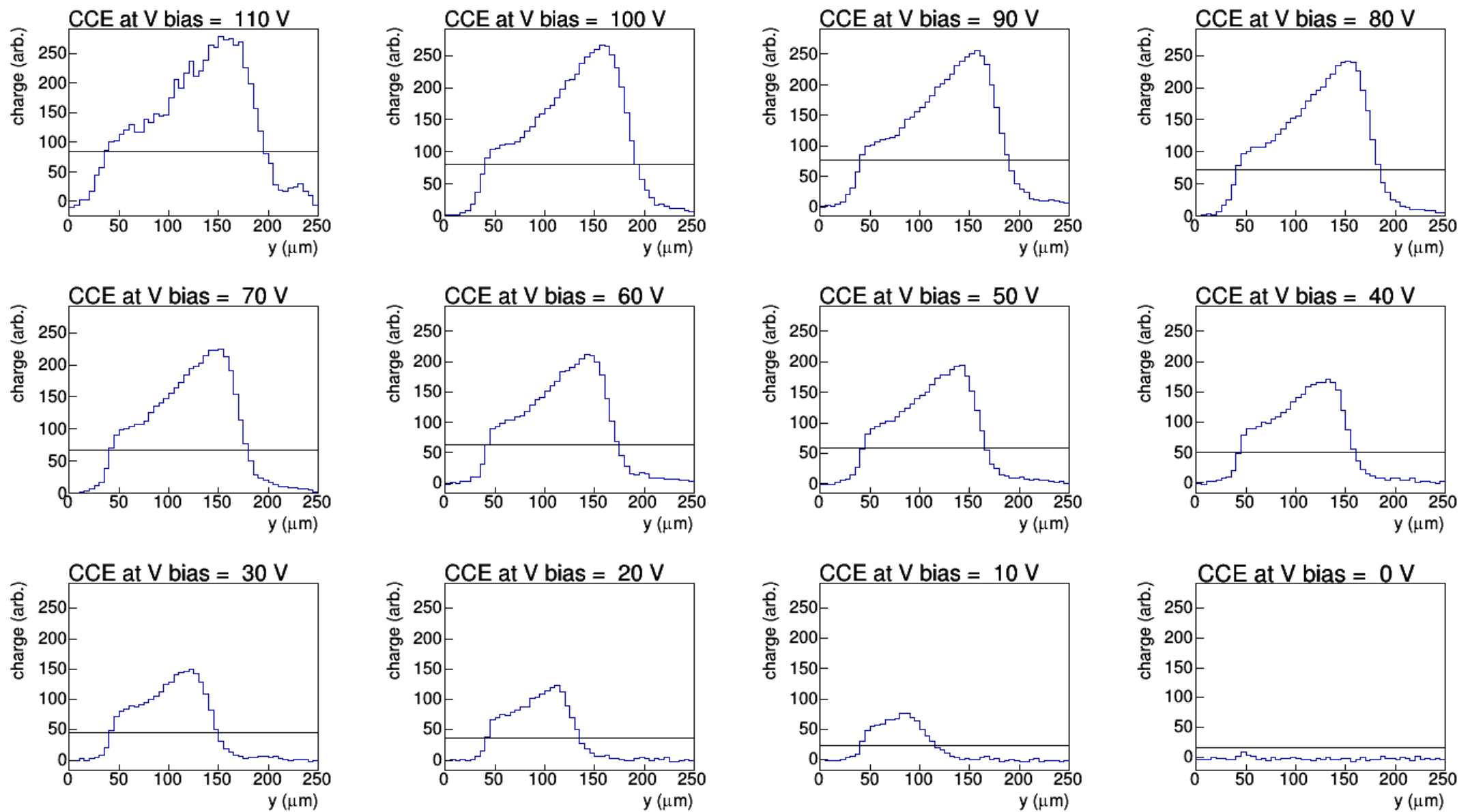
- Collected charge before and after annealing (80 min at 60 °C)
- After annealing about 10 % increase in charge
- Later electrical breakdown in annealed samples

# Charge collection profiles 20 $\Omega\cdot\text{cm}$ (7.8e14p)

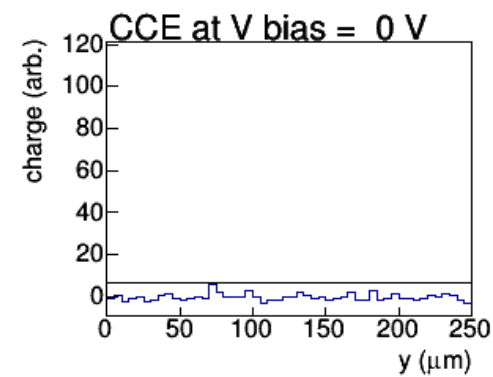
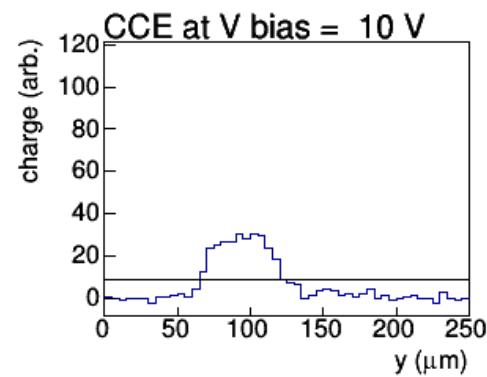
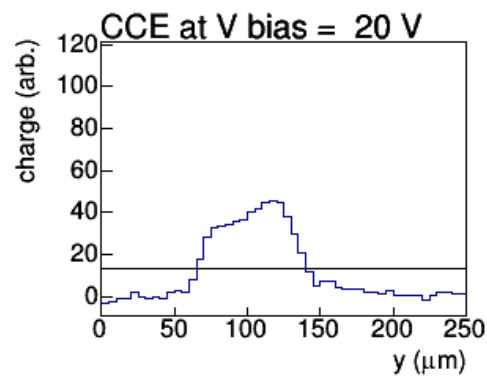
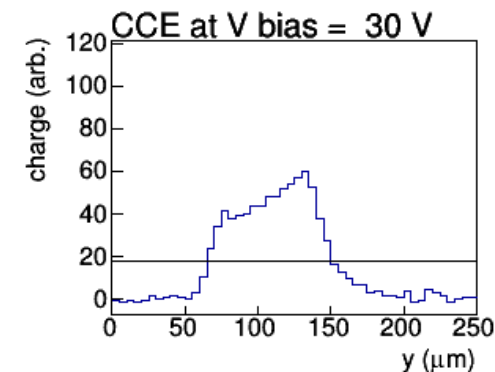
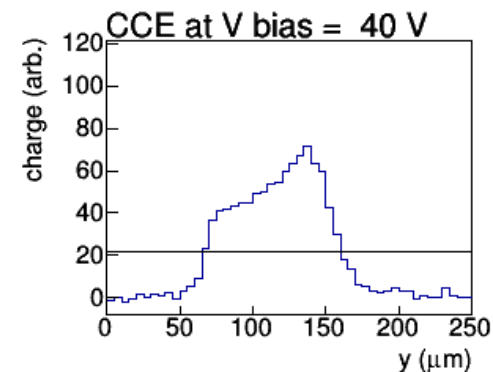
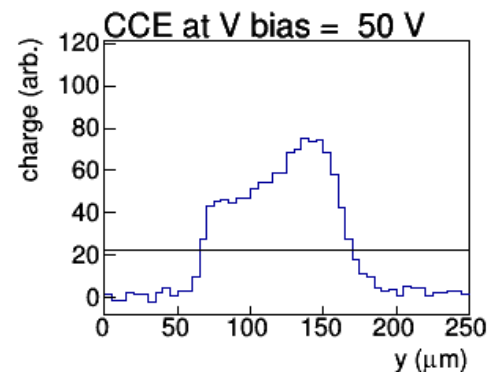
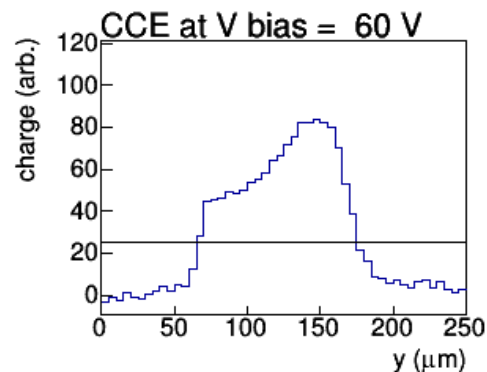
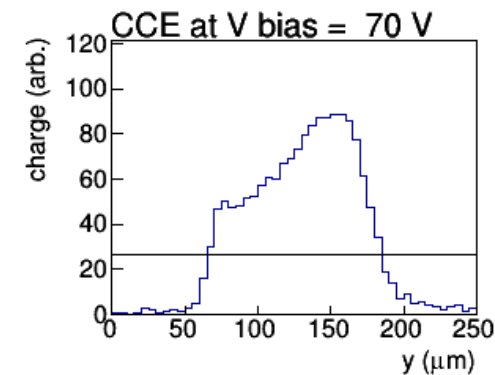
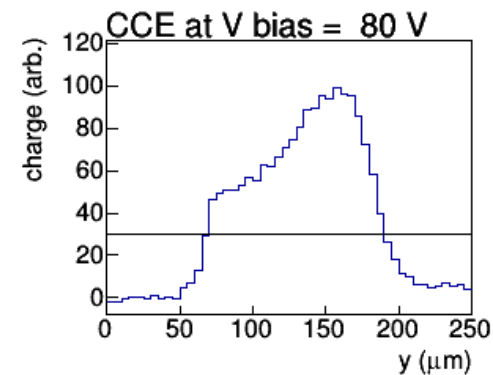
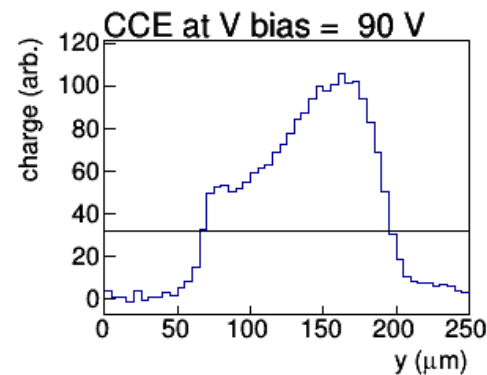
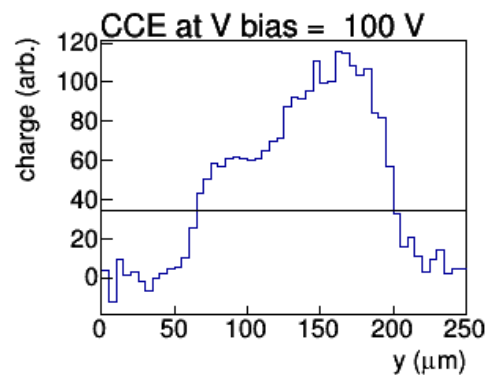




# Charge collection profiles 50 $\Omega\cdot\text{cm}$ (1.4e15p)



# Charge collection profiles 200 $\Omega\cdot\text{cm}$ (3.6e15p)



# Charge collection profiles 1000 $\Omega\cdot\text{cm}$ (7.8e14p)

